

METHOD AND DEVICE FOR SEPARATING A REINFORCING-PLATE FIXED TO A REINFORCED SEMICONDUCTOR WAFER

ABSTRACT OF THE DISCLOSURE

5 In a method for separating a reinforcing-plate fixed to a
reinforced semiconductor wafer, the wafer includes a
semiconductor wafer on which a pattern is formed and a double-
side adhesive sheet having, on at least one surface thereof, a
peelable adhesive layer, wherein the peelable adhesive layer is
10 stuck to a front face of the semiconductor wafer and the
reinforcing-plate is fixed to the other adhesive layer of the double-
side adhesive sheet. The reinforcing-plate is separated together
with the double-side adhesive sheet from the reinforced
semiconductor wafer by the peeling-effect of the peelable adhesive
15 layer of the double-side adhesive sheet. Furthermore, the
reinforcing-plate is separated from an arbitrarily selected edge of
the semiconductor wafer toward an edge thereof different from the
above-mentioned edge. This makes it possible to separate the
reinforcing-plate, without breaking the semiconductor wafer, from
20 the reinforced semiconductor wafer to which the reinforcing-plate
is fixed through the double-side adhesive sheet having the peelable
adhesive layer.

Fig. 1(a) - (d)